

## N-Channel Enhancement Mode Power MOSFET

### DESCRIPTION

The PTH F€ uses advanced trench technology and design to provide excellent  $R_{DS(ON)}$  with low gate charge. It can be used in a wide variety of applications.

### GENERAL FEATURES

- $V_{DS} = 100V, I_D = 57A$
- $R_{DS(ON)} < 16m\Omega @ V_{GS}=10V$  (Typ:12mΩ)

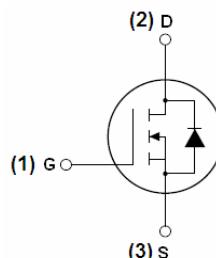
- Special process technology for high ESD capability
- High density cell design for ultra low  $R_{Dson}$
- Fully characterized Avalanche voltage and current
- Good stability and uniformity with high  $E_{AS}$
- Excellent package for good heat dissipation

### Application

- Power switching application
- Hard Switched and High Frequency Circuits
- Uninterruptible Power Supply

**100% UIS TESTED!**

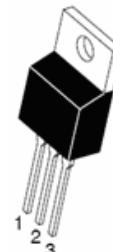
**100%  $\Delta V_{ds}$  TESTED!**



Schematic diagram



Marking and pin Assignment



TO-220 top view

### Package Marking And Ordering Information

Device Marking	Device	Device Package	Reel Size	Tape width	Quantity
PTH F€	PTH F€	TO-220	-	-	-

### Absolute Maximum Ratings (TA=25°C unless otherwise noted)

Parameter	Symbol	Limit	Unit
Drain-Source Voltage	$V_{DS}$	100	V
Gate-Source Voltage	$V_{GS}$	$\pm 20$	V
Drain Current-Continuous	$I_D$	57	A
Drain Current-Continuous( $T_C=100^\circ C$ )	$I_D (100^\circ C)$	40	A
Pulsed Drain Current	$I_{DM}$	190	A
Maximum Power Dissipation	$P_D$	170	W
Derating factor		1.13	W/°C
Single pulse avalanche energy (Note 5)	$E_{AS}$	580	mJ
Operating Junction and Storage Temperature Range	$T_J, T_{STG}$	-55 To 175	°C

### Thermal Characteristic

Thermal Resistance,Junction-to-Case(Note 2)	R <sub>θJC</sub>	0.88	°C/W
---	------------------	------	------

### Electrical Characteristics (TA=25°C unless otherwise noted)

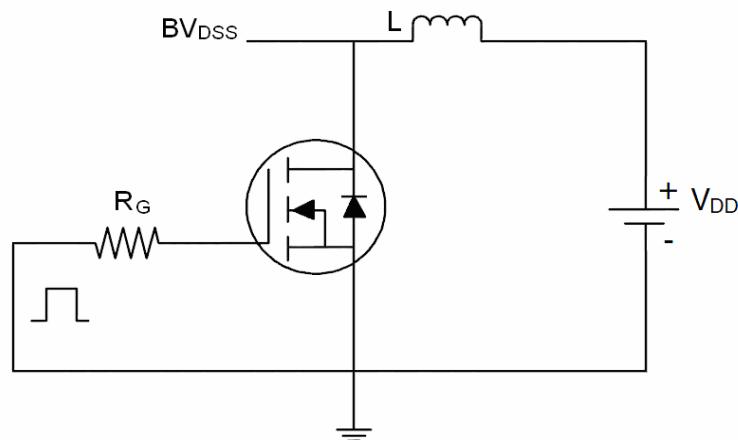
Parameter	Symbol	Condition	Min	Typ	Max	Unit
<b>Off Characteristics</b>						
Drain-Source Breakdown Voltage	BV <sub>DSS</sub>	V <sub>GS</sub> =0V I <sub>D</sub> =250μA	100	110	-	V
Zero Gate Voltage Drain Current	I <sub>DSS</sub>	V <sub>DS</sub> =100V, V <sub>GS</sub> =0V	-	-	1	μA
Gate-Body Leakage Current	I <sub>GSS</sub>	V <sub>GS</sub> =±20V, V <sub>DS</sub> =0V	-	-	±100	nA
<b>On Characteristics (Note 3)</b>						
Gate Threshold Voltage	V <sub>GS(th)</sub>	V <sub>DS</sub> =V <sub>GS</sub> , I <sub>D</sub> =250μA	2	3	4	V
Drain-Source On-State Resistance	R <sub>DSON</sub>	V <sub>GS</sub> =10V, I <sub>D</sub> =28A	-	12	16	mΩ
Forward Transconductance	g <sub>FS</sub>	V <sub>DS</sub> =25V, I <sub>D</sub> =28A	32	-	-	S
<b>Dynamic Characteristics (Note 4)</b>						
Input Capacitance	C <sub>iss</sub>	V <sub>DS</sub> =25V, V <sub>GS</sub> =0V, F=1.0MHz	-	4400	-	PF
Output Capacitance	C <sub>oss</sub>		-	320	-	PF
Reverse Transfer Capacitance	C <sub>rss</sub>		-	240	-	PF
<b>Switching Characteristics (Note 4)</b>						
Turn-on Delay Time	t <sub>d(on)</sub>	V <sub>DD</sub> =50V, I <sub>D</sub> =28A V <sub>GS</sub> =10V, R <sub>GEN</sub> =2.5Ω	-	12	-	nS
Turn-on Rise Time	t <sub>r</sub>		-	55	-	nS
Turn-Off Delay Time	t <sub>d(off)</sub>		-	45	-	nS
Turn-Off Fall Time	t <sub>f</sub>		-	47	-	nS
Total Gate Charge	Q <sub>g</sub>	V <sub>DS</sub> =80V, I <sub>D</sub> =28A, V <sub>GS</sub> =10V	-	95	-	nC
Gate-Source Charge	Q <sub>gs</sub>		-	18	-	nC
Gate-Drain Charge	Q <sub>gd</sub>		-	25	-	nC
<b>Drain-Source Diode Characteristics</b>						
Diode Forward Voltage (Note 3)	V <sub>SD</sub>	V <sub>GS</sub> =0V, I <sub>S</sub> =28A	-	0.85	1.2	V
Diode Forward Current (Note 2)	I <sub>S</sub>		-	-	57	A
Reverse Recovery Time	t <sub>rr</sub>	T <sub>J</sub> = 25°C, IF = 28A di/dt = 100A/μs(Note3)	-	36	-	nS
Reverse Recovery Charge	Q <sub>rr</sub>		-	56	-	nC
Forward Turn-On Time	t <sub>on</sub>	Intrinsic turn-on time is negligible (turn-on is dominated by LS+LD)				

### Notes:

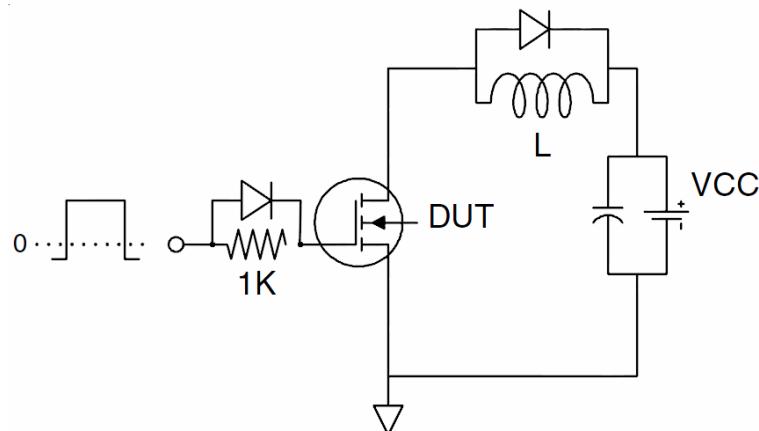
1. Repetitive Rating: Pulse width limited by maximum junction temperature.
2. Surface Mounted on FR4 Board, t ≤ 10 sec.
3. Pulse Test: Pulse Width ≤ 300μs, Duty Cycle ≤ 2%.
4. Guaranteed by design, not subject to production
5. EAS condition: T<sub>j</sub>=25°C, V<sub>DD</sub>=50V, V<sub>G</sub>=10V, L=0.5mH, R<sub>g</sub>=25Ω

## Test circuit

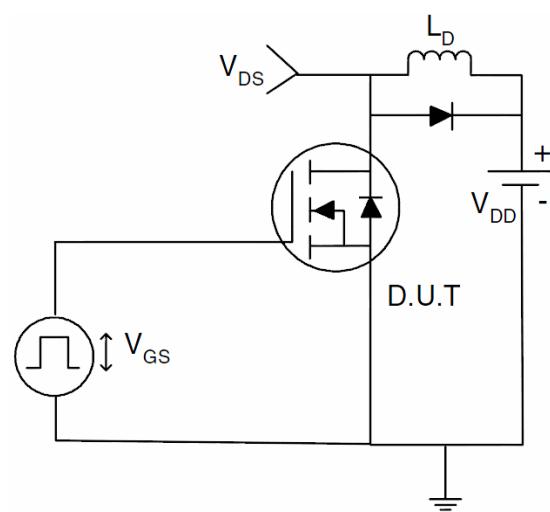
### 1) E<sub>AS</sub> test Circuits



### 2) Gate charge test Circuit:



### 3) Switch Time Test Circuit:



### TYPICAL ELECTRICAL AND THERMAL CHARACTERISTICS (Curves)

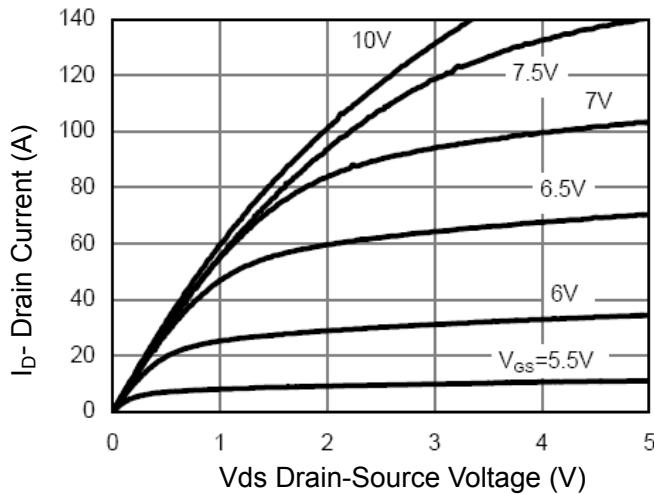


Figure 1 Output Characteristics

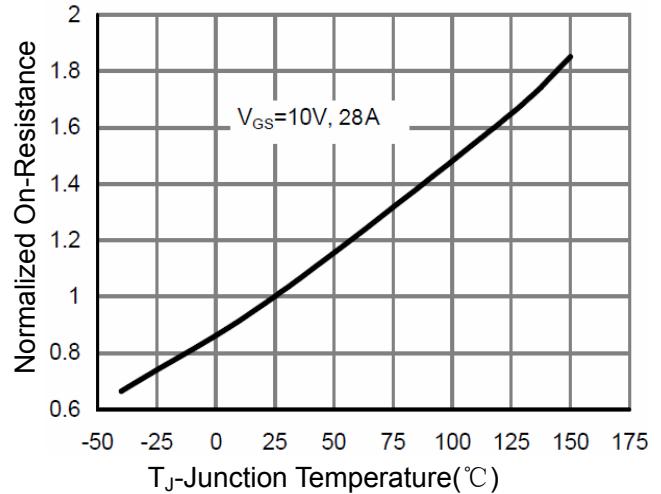


Figure 4 Rdson-JunctionTemperature

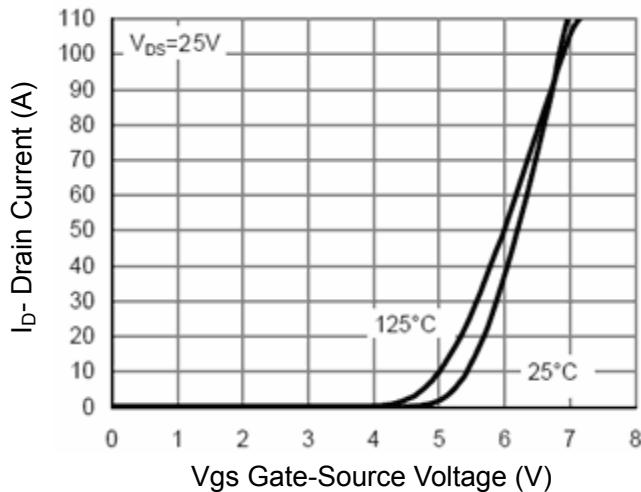


Figure 2 Transfer Characteristics

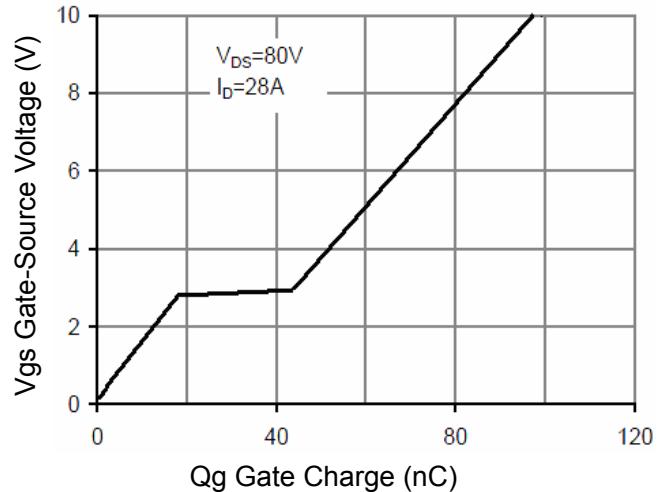


Figure 5 Gate Charge

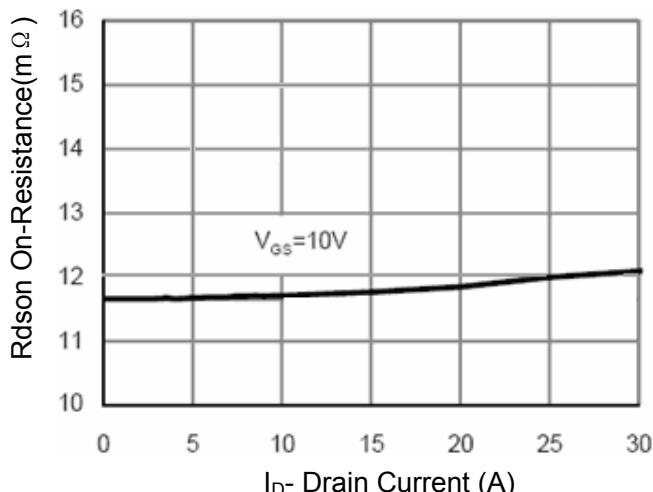


Figure 3 Rdson- Drain Current

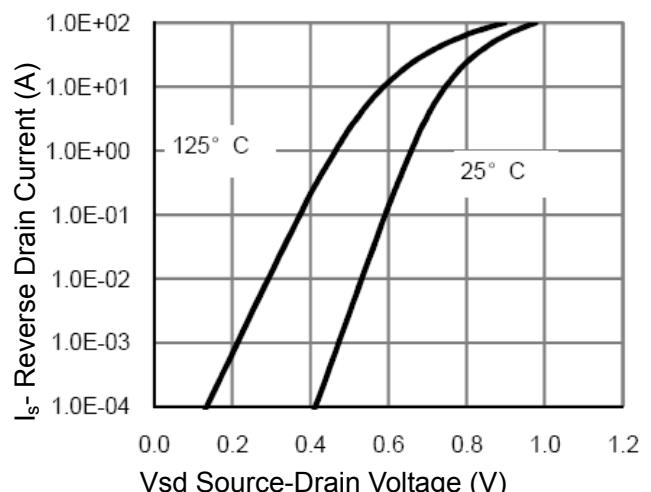


Figure 6 Source- Drain Diode Forward

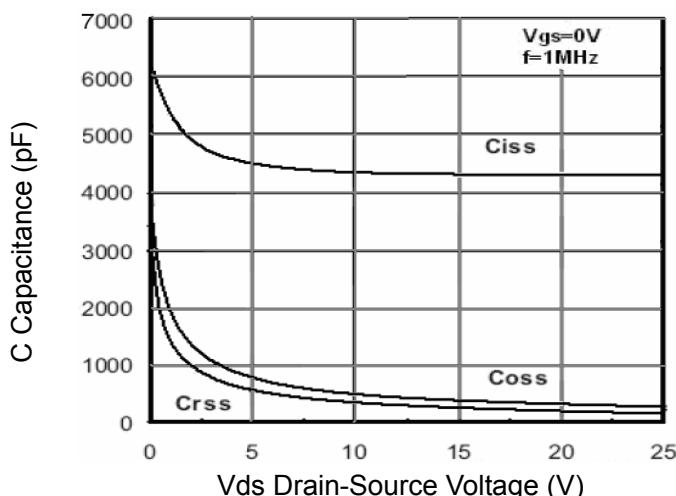


Figure 7 Capacitance vs Vds

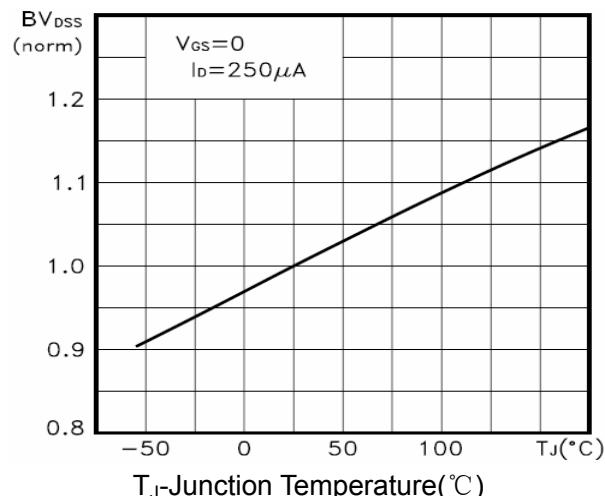


Figure 9  $BV_{DSS}$  vs Junction Temperature

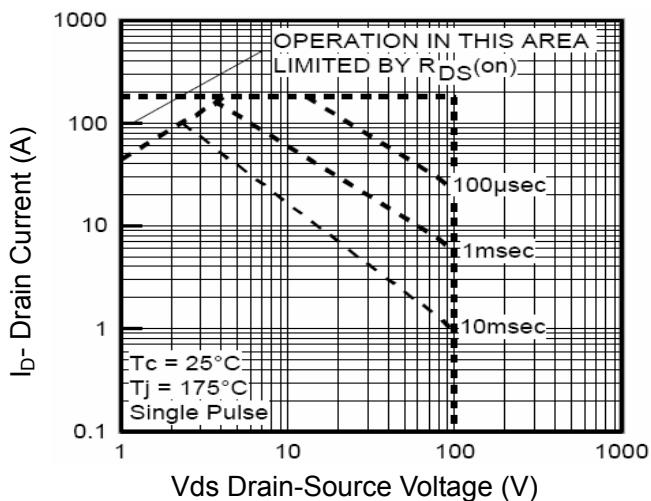


Figure 8 Safe Operation Area

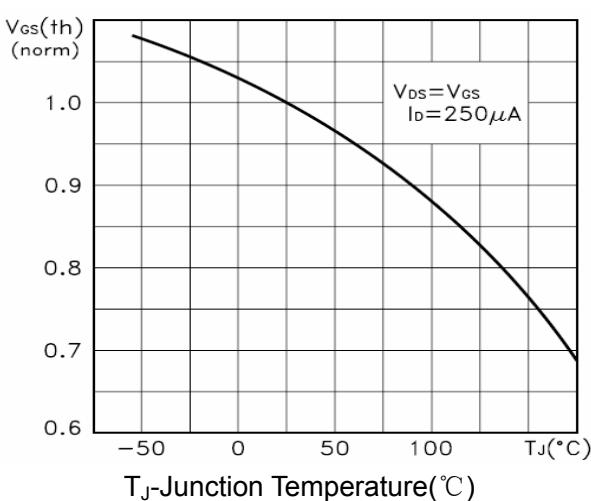


Figure 10  $V_{GS(th)}$  vs Junction Temperature

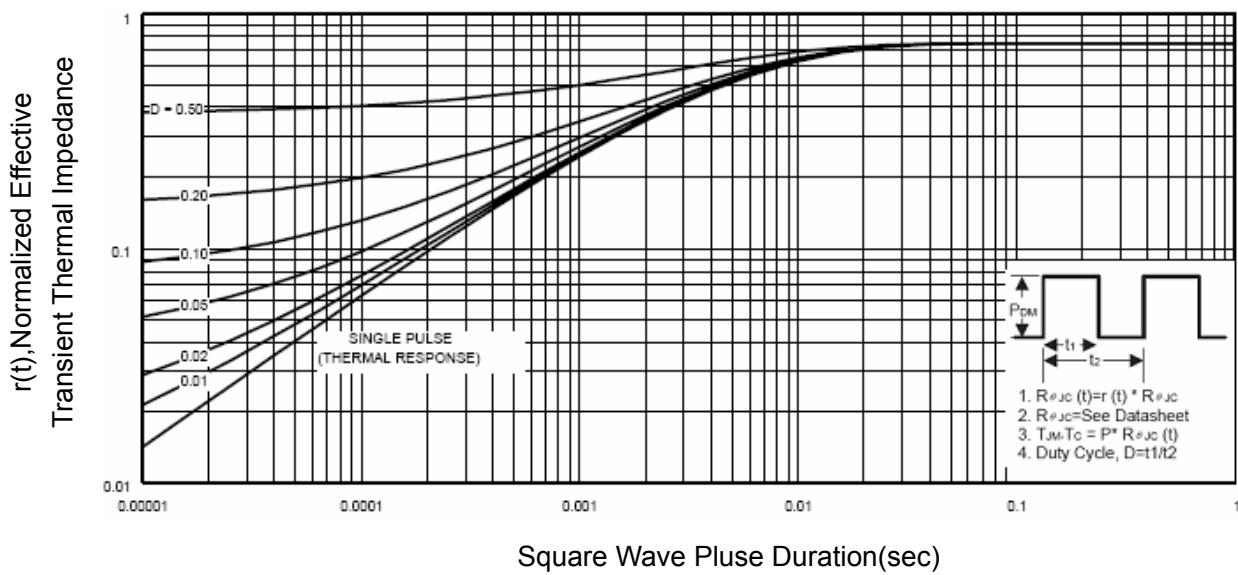
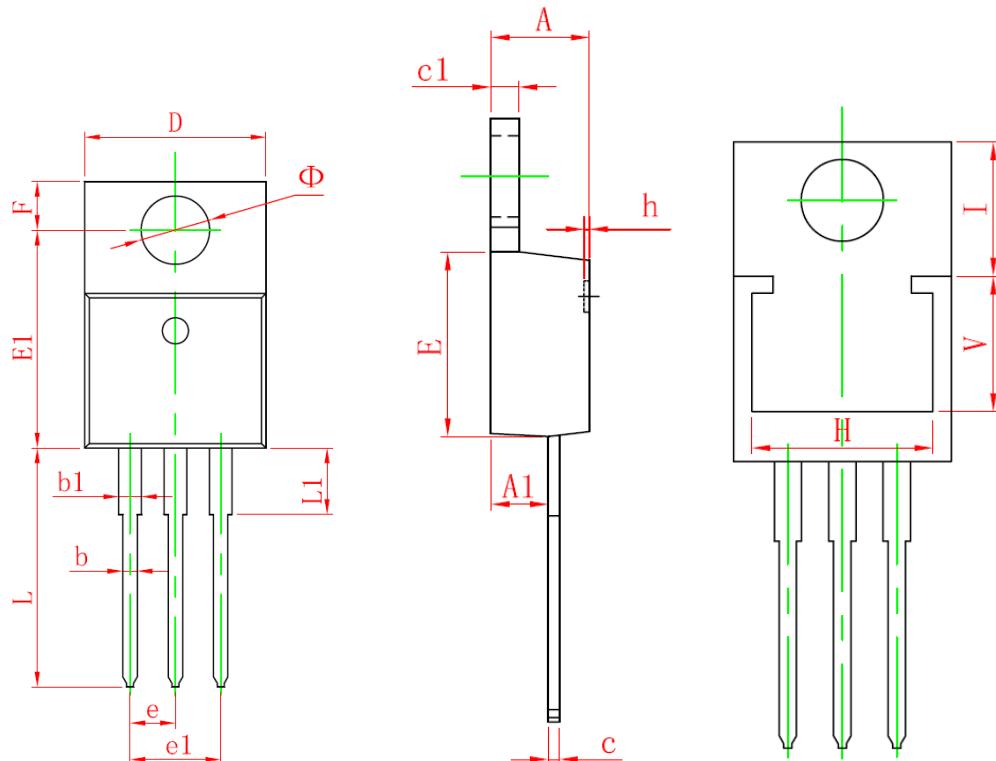


Figure 11 Normalized Maximum Transient Thermal Impedance

## TO-220-3L Package Information



Symbol	Dimensions In Millimeters		Dimensions In Inches	
	Min	Max	Min	Max
A	4.470	4.670	0.176	0.184
A1	2.520	2.820	0.099	0.111
b	0.710	0.910	0.028	0.036
b1	1.170	1.370	0.046	0.054
c	0.330	0.650	0.013	0.026
c1	1.200	1.400	0.047	0.055
D	10.010	10.350	0.394	0.407
E	8.500	8.900	0.335	0.350
E1	12.060	12.460	0.475	0.491
e	2.540 (TYP.)		0.100 (TYP.)	
e1	4.980	5.180	0.196	0.204
F	2.590	2.890	0.102	0.114
H	8.440 REF.		0.332 REF.	
h	0.000	0.300	0.000	0.012
L	13.400	13.800	0.528	0.543
L1	3.560	3.960	0.140	0.156
V	6.360 REF.		0.250 REF.	
I	6.300 REF.		0.248 REF.	
Φ	3.735	3.935	0.147	0.155